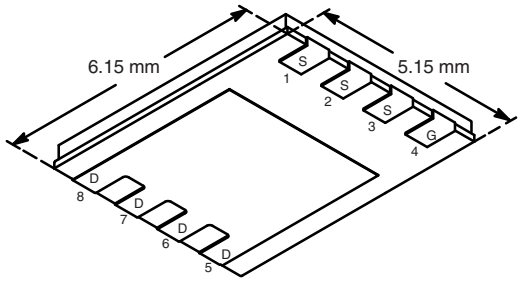
N-Channel 60 V (D-S) Reduced Q_{gd}, Fast Switching MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]	Q_g (Typ.)
60	0.0078 at V_{GS} = 10 V	30	55
	0.009 at V_{GS} = 6 V	30	

PowerPAK SO-8



Bottom View

Ordering Information: Si7138DP-T1-E3 (Lead (Pb)-free)
Si7138DP-T1-GE3 (Lead (Pb)-free) and Halogen-free)

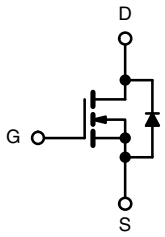
FEATURES

- **Halogen-free According to IEC 61249-2-21 Definition**
- Low Thermal Resistance PowerPAK® Package
- 100 % R_g and Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC

Pb-free
RoHS COMPLIANT
HALOGEN FREE Available

APPLICATIONS

- Primary Side Switch
  - Very Low R_g and Q_{gd}, Critical for Minimizing Losses



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)				
Parameter		**Symbol**	**Limit**	**Unit**
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	30	A
	T_C = 70 °C		30	
	T_A = 25 °C		19.7[b, c]	
	T_A = 70 °C		15.7[b, c]	
Pulsed Drain Current		I_{DM}	80	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	30[a]	
	T_A = 25 °C		4.5[b, c]	
Avalanche Current	L = 0.1 mH	I_{AS}	43	
Single-Pulse Avalanche Energy		E_{AS}	93	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	96	W
	T_C = 70 °C		61.5	
	T_A = 25 °C		5.4[b, c]	
	T_A = 70 °C		3.5[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature)[d, e]			260	

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Maximum Junction-to-Ambient[b, f]	t ≤ 10 s	R_{thJA}	18	23	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.0	1.5	

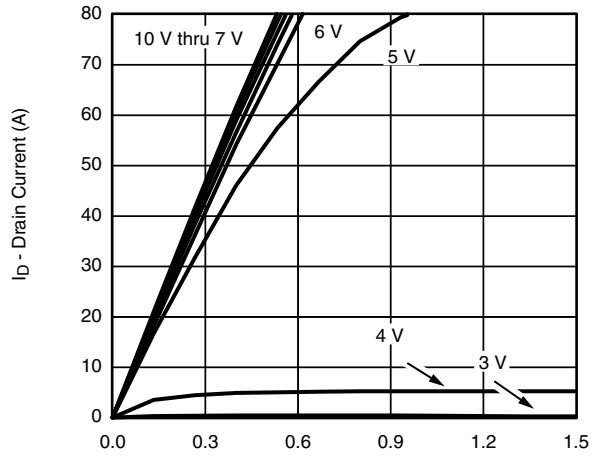
Notes:
a. Package limited.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. See solder profile (www.vishay.com/ppg?73461). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
f. Maximum under steady state conditions is 65 °C/W.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 1 mA	60			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA		60.5		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 8.4		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	2		4	
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			1	µA
		V_{DS} = 60 V, V_{GS} = 0 V, T_J = 55 °C			10	
On-State Drain Current[a]	$I_{D(on)}$	$V_{DS} \geq$ 5 V, V_{GS} = 10 V	30			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 19.7 A		0.0065	0.0078	Ω
		V_{GS} = 6 V, I_D = 18 A		0.0073	0.009	
Forward Transconductance[a]	g_{fs}	V_{DS} = 15 V, I_D = 19.7 A		84		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz		6900		pF
Output Capacitance	C_{oss}			470		
Reverse Transfer Capacitance	C_{rss}			200		
Total Gate Charge	Q_g	V_{DS} = 30 V, V_{GS} = 10 V, I_D = 19.7 A		90	135	nC
		V_{DS} = 30 V, V_{GS} = 6 V, I_D = 19.7 A		55	83	
Gate-Source Charge	Q_{gs}			27.5		
Gate-Drain Charge	Q_{gd}			11		
Gate Resistance	R_g	f = 1 MHz		0.6	0.9	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 30 V, R_L = 3 Ω $I_D \cong$ 10 A, V_{GEN} = 6 V, R_g = 1 Ω		47	70	ns
Rise Time	t_r			120	180	
Turn-Off Delay Time	$t_{d(off)}$			40	60	
Fall Time	t_f			8	15	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 30 V, R_L = 3 Ω $I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		25	40	
Rise Time	t_r			12	20	
Turn-Off Delay Time	$t_{d(off)}$			50	75	
Fall Time	t_f			8	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			30	A
Pulse Diode Forward Current[a]	I_{SM}				80	
Body Diode Voltage	V_{SD}	I_S = 2.7 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 10 A, dI/dt = 100 A/µs, T_J = 25 °C		45	70	ns
Body Diode Reverse Recovery Charge	Q_{rr}			80	120	nC
Reverse Recovery Fall Time	t_a			30		ns
Reverse Recovery Rise Time	t_b			15		

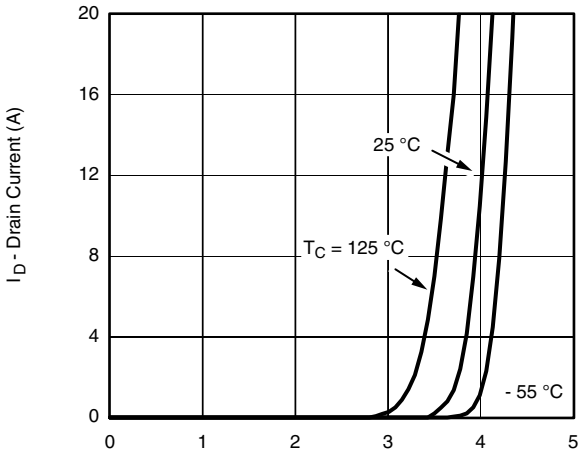
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

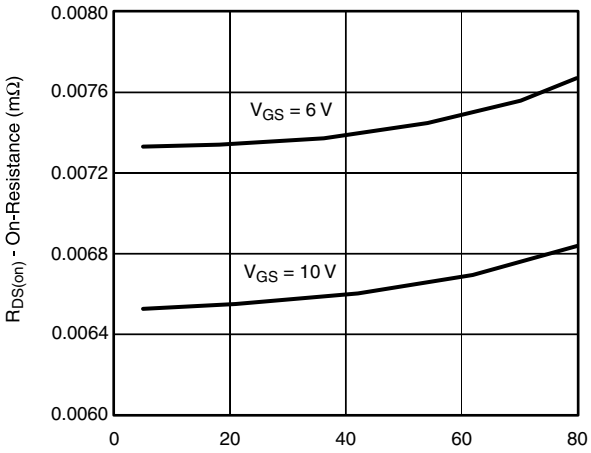
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



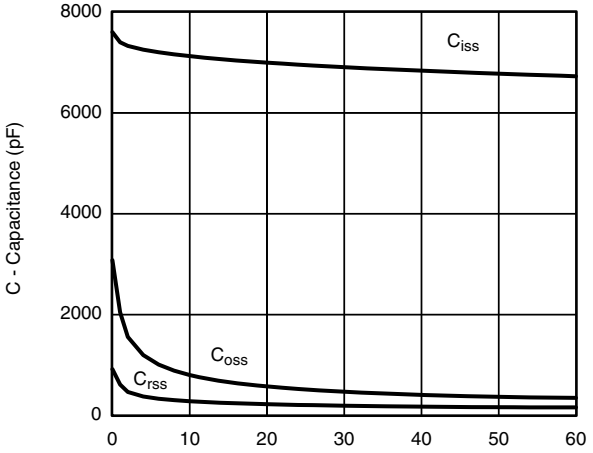
Output Characteristics



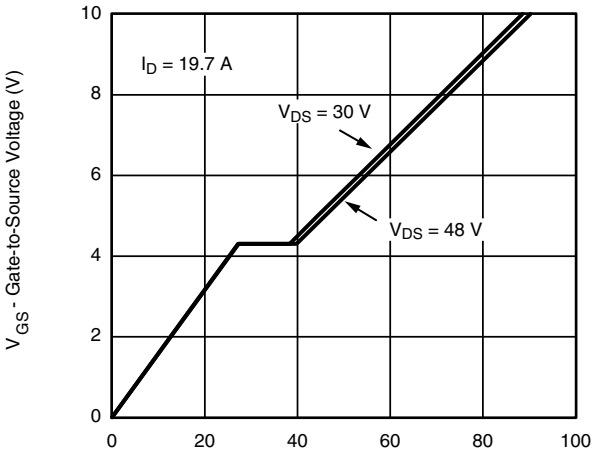
Transfer Characteristics



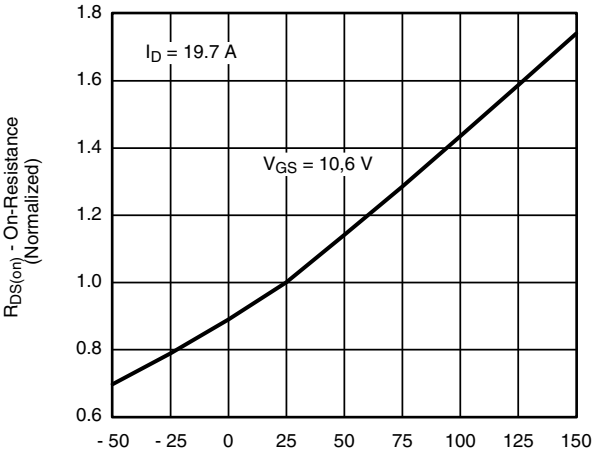
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

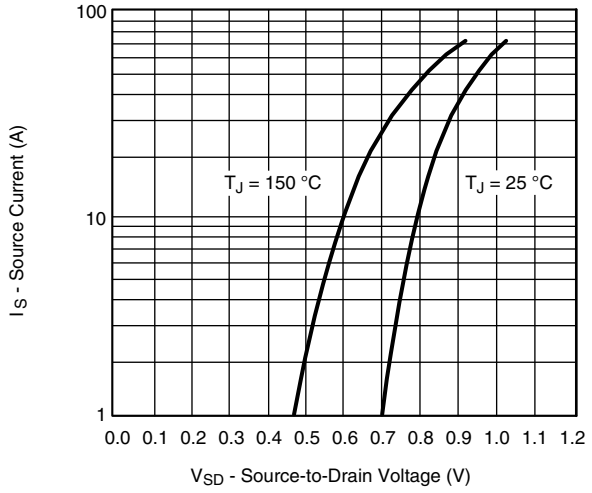


Gate Charge

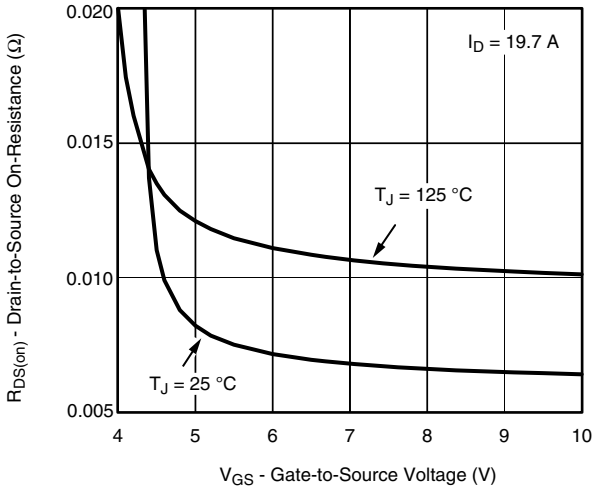


On-Resistance vs. Junction Temperature

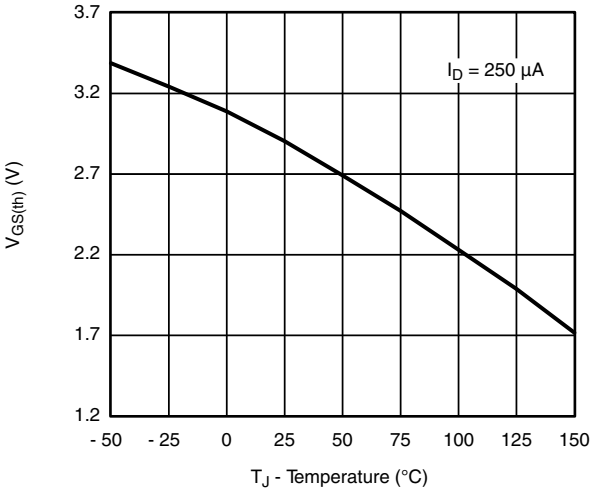
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



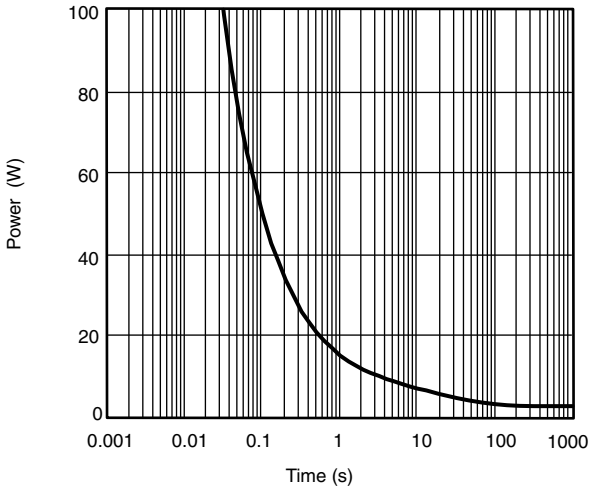
Source-Drain Diode Forward Voltage



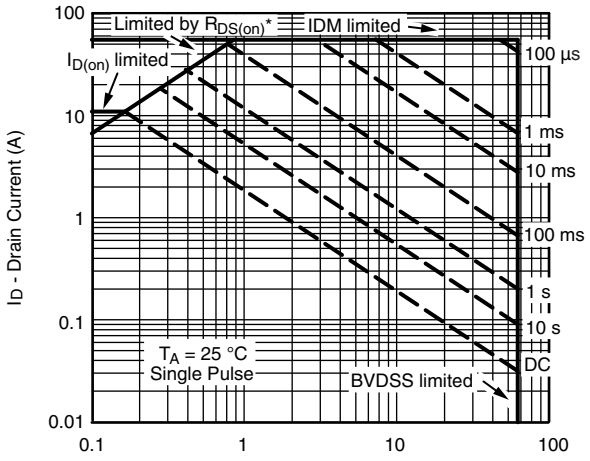
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



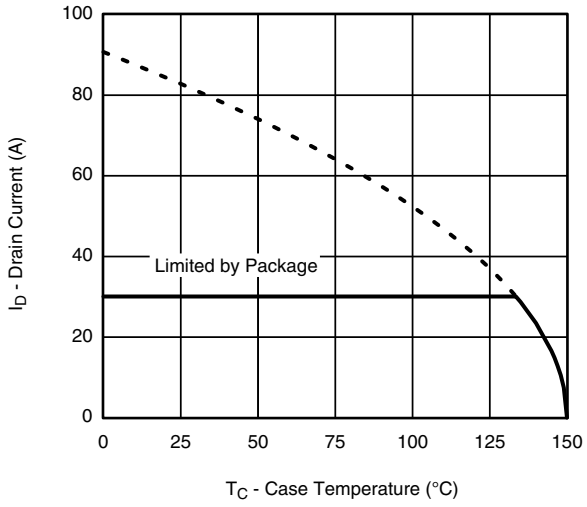
Single Pulse Power, Junction-to-Ambient



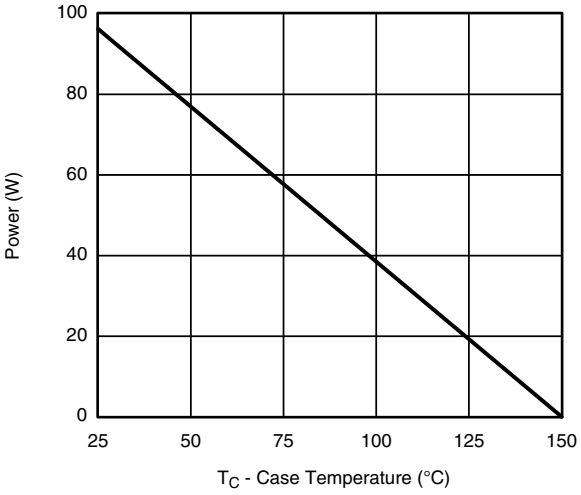
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

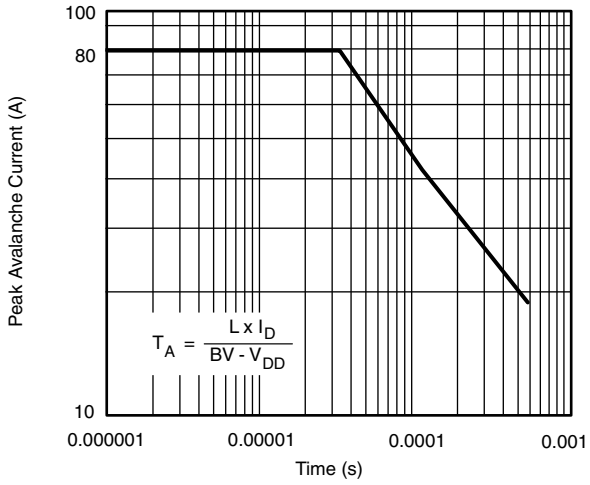
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



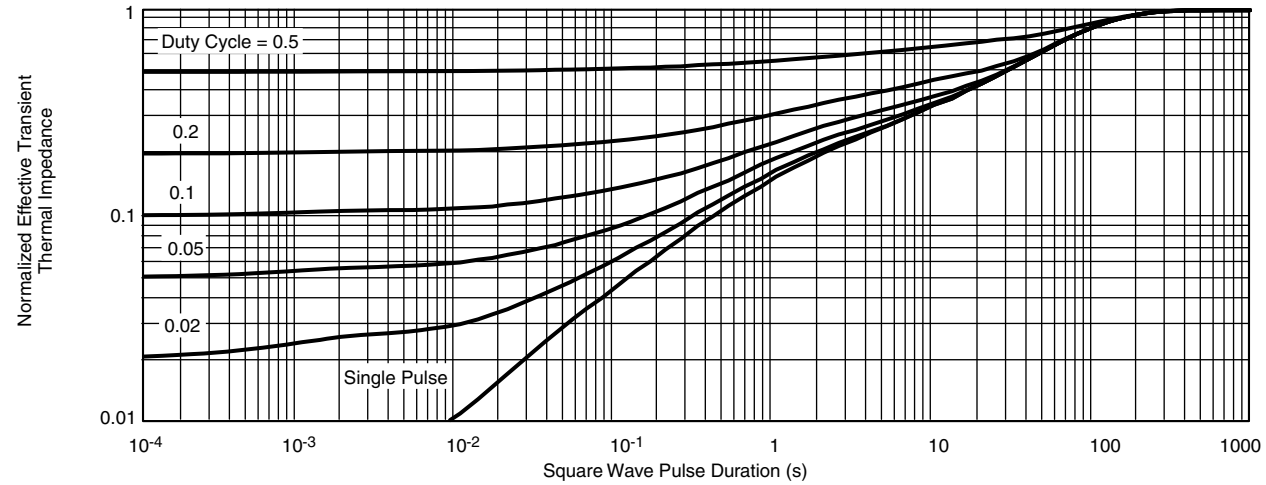
Power Derating (Junction-to-Case)



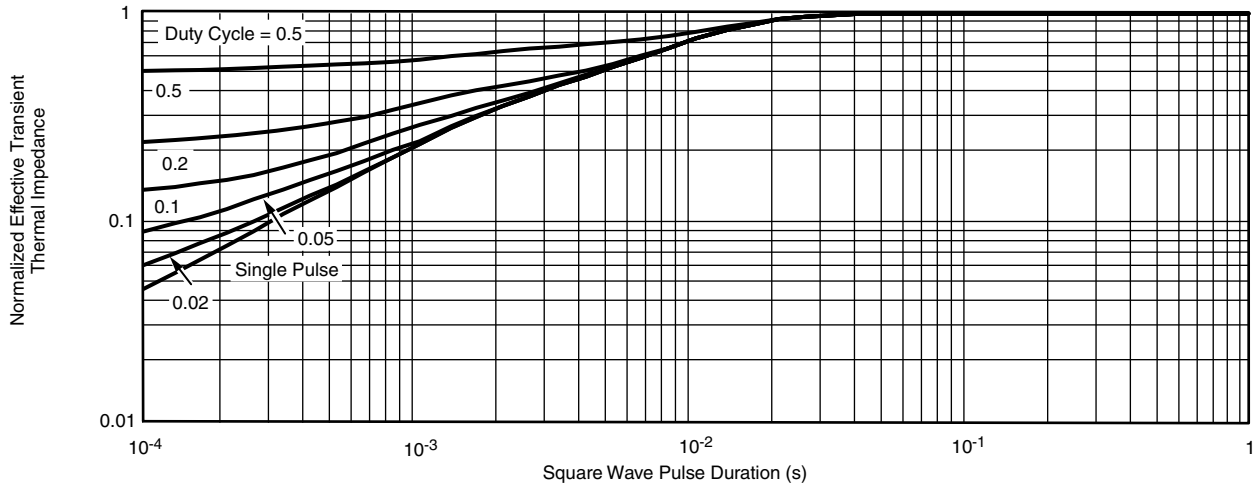
Maximum Single Pulse Avalanche Capability

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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